Form No: XXXXXX-7-0000-PBM03-190300422

Specification for Approval

Date: 2019/03/27

Customer : Qisda

TAI-TECH P/N: TMPC1004H-100MG-D

CUSTOMER P/N: 6H.10010.20V

DESCRIPTION:

QUANTITY: pcs

REMARK:		
Customer Approval Feedback		

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SMD Power Inductor

TMPC1004H-100MG-D

ECN HISTORY LIST

REV	DATE	DESCRIPTION	APPROVED	CHECKED	DRAWN
1.0	19/03/27	新發行(因供應商順和停產，更換成日立)	羅宜春	梁周虎	許靜

SMD Power Inductor

TMPC1004H-100MG-D

1. Features

1. Carbonyl Powder.
2. Compact design.
3. High current，low DCR，high efficiency.
4. Very low acoustic noise and very low leakage flux noise.
5. High reliability.
6. 100% Lead(Pb)-Free and RoHS compliant.
7. Operating temperature -40~+125℃(Including self - temperature rise)

Halogen-free

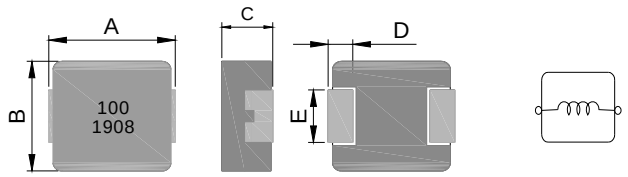
RoHS

2. Applications

Note PC power system，incl. IMVP-6

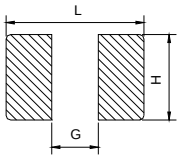
DC/DC converter .

3. Dimensions



Series	A(mm)	B(mm)	C(mm)	D(mm)	E(mm)
TMPC1004H	11.0±0.5	10.0±0.3	3.8±0.2	2.3±0.3	3.0±0.3

Recommend PC Board Pattern



L(mm)	G(mm)	H(mm)
13.6	5.4	3.5

Note: 1. The above PCB layout reference only.
2. Recommend solder paste thickness at 0.15mm and above.

4. Part Numbering

TMPC	1004	H	-	100	MG	-	D
A	B	C		D	E		F

A: Series
B: Dimension — BxC
C: Type — Carbonyl Powder.
D: Inductance — 100=10.0uH
E: Inductance Tolerance — M=±20%
F: Code — Marking: Black.100 and 1908(19 YY, 08 WW,follow production date).

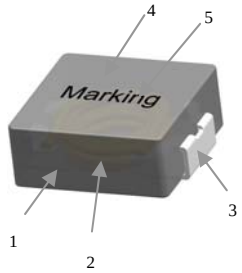
5. Specification

Part Number	Inductance L0 (uH)±20%	I rms (A)		I sat (A)		DCR (mΩ)Typ. @25℃	DCR (mΩ) Max. @25℃	SRF (MHz) Ref
		Typ	Max	Typ	Max			
TMPC1004H-100MG-D	10.0	7.5	6.3	12	11	27	30	10

Note:

1. Test frequency : Ls : 100KHz /1.0V.
2. All test data referenced to 25℃ ambient.
3. Testing Instrument(or equ) : L: HP4284A,CH11025,CH3302,CH1320,CH1320S LCR METER / Rdc:CH16502,Agilent33420A MICRO OHMMETER.
4. Heat Rated Current (Irms) will cause the coil temperature rise approximately ΔT of 40℃
5. Saturation Current (Isat) will cause L0 to drop approximately 30%.
6. The part temperature (ambient + temp rise) should not exceed 125℃under worst case operating conditions.Circuit design,component,PCB trace size and thickness,airflow and other cooling provisions all affect the part temperature. Part temperature should be verified in the end application.
7. Special inquiries besides the above common used types can be met on your requirement.

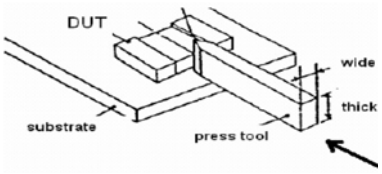
6. Material List



NO	Items	Materials
1	Core	Carbonyl Powder.
2	Wire	Polyester Wire or equivalent. (AIW 220℃ Class)
3	Clip	100% Pb free solder(Ni+Sn---Plating)
4	Ink	Halogen-free ketone
5	paint	Epoxy resin

7. Reliability and Test Condition

Item	Performance	Test Condition
Operating temperature	-40~+125℃ (Including self - temperature rise)	
Storage temperature	1.-10~+40℃,50~60%RH (Product with taping) 2.-40~+125℃ (on board)	
Electrical Performance Test		
Inductance	Refer to standard electrical characteristics list.	HP4284A,CH11025,CH3302,CH1320,CH1320S LCR Meter.
DCR		CH16502,Agilent33420A Micro-Ohm Meter.
Saturation Current (Isat)	Approximately △L30%.	Saturation DC Current (Isat) will cause L0 to drop △L(%)
Heat Rated Current (Irms)	Approximately △T40℃	Heat Rated Current (Irms) will cause the coil temperature rise △T(℃). 1.Applied the allowed DC current 2.Temperature measured by digital surface thermometer
Reliability Test		
Life Test	Appearance：No damage. Impedance：within±15% of initial value Inductance：within±10% of initial value Q：Shall not exceed the specification value. RDC：within ±15% of initial value and shall not exceed the specification value	Preconditioning: Run through IR reflow for 2 times.(IPC/JEDECJ-STD-020DClassification Reflow Profiles) Temperature： 125±2℃(Inductor) Applied current：rated current Duration：1000±12hrs Measured at room temperature after placing for 24±2 hrs.
Load Humidity		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDECJ-STD-020DClassification Reflow Profiles) Humidity：85±2% R.H, Temperature：85℃±2℃ Duration：1000hrs Min. with 100% rated current Measured at room temperature after placing for 24±2 hrs.
Low Temperature Unload Life Test		Preconditioning:Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles Temperature:-40±2℃ Time: 500±8hr. Recovery: 4 to 24hrs of recovery under the standard condition after the removal from test chamber.
Moisture Resistance		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDECJ-STD-020DClassification Reflow Profiles) 1. Baked at50℃ for 25hrs, measured at room temperature after placing for 4 hrs. 2. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs. 3. Raise temperature to 65±2℃ 90-100%RH in 2.5hrs, and keep 3 hours, cool down to 25℃ in 2.5hrs,keep at 25℃ for 2 hrs then keep at -10℃ for 3 hrs 4. Keep at 25℃ 80-100%RH for 15min and vibrate at the frequency of 10 to 55 Hz to 10 Hz, measure at room temperature after placing for 1~2 hrs.
Thermal shock		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDECJ-STD-020DClassification Reflow Profiles) Condition for 1 cycle Step1：-40±2℃ 30±5min Step2：25±2℃ ≦0.5min Step3：125±2℃ 30±5minNumber of cycles： 500 Measured at room fempraturc after placing for 24±2 hrs.
Vibration		Preconditioning: Run through IR reflow for 2 times.(IPC/JEDECJ-STD-020DClassification Reflow Profiles) Oscillation Frequency: 10～2K～10Hz for 20 minutes Equipment： Vibration checker Total Amplitude:1.52mm±10% Testing Time : 12 hours(20 minutes, 12 cycles each of 3 orientations)。

<table>
<tr><th>Item</th><th>Performance</th><th>Test Condition</th></tr>
<tr><td>Bending</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value</td><td>Shall be mounted on a FR4 substrate of the following dimensions: >=0805 inch(2012mm):40x100x1.2mm
<0805 inch(2012mm):40x100x0.8mm
Bending depth: >=0805 inch(2012mm):1.2mm
<0805 inch(2012mm):0.8mm
duration of 10 sec.</td></tr>
<tr><td>Shock</td><td><table><tr><td>Type</td><td>Peak value (g's)</td><td>Normal duration (D) (ms)</td><td>Wave form</td><td>Velocity change (Vi)ft/sec</td></tr><tr><td>SMD</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr><tr><td>Lead</td><td>50</td><td>11</td><td>Half-sine</td><td>11.3</td></tr></table></td></tr>
<tr><td>Solder ability</td><td>More than 95% of the terminal electrode should be covered with solder。</td><td>Preheat: 150℃,60sec.。
Solder: Sn96.5% Ag3% Cu0.5%
Temperature: 245±5℃。
Flux for lead free: Rosin. 9.5%。
Dip time: 4±1sec。
Depth: completely cover the termination</td></tr>
<tr><td>Resistance to Soldering Heat</td><td rowspan="2">Appearance：No damage.
Impedance：within±15% of initial value
Inductance：within±10% of initial value
Q：Shall not exceed the specification value.
RDC：within ±15% of initial value and shall not exceed the specification value e</td><td>Depth: completely cover the termination<table><tr><td>Temperature(°C)</td><td>Time(s)</td><td>Temperature ramp/immersion and emersion rate</td><td>Number of heat cycles</td></tr><tr><td>260 ±5 (solder temp)</td><td>10 ±1</td><td>25mm/s ±6 mm/s</td><td>1</td></tr></table></td></tr>
<tr><td>Terminal Strength</td><td>Preconditioning: Run through IR reflow for 2 times.(IPC/JEDEC J-STD-020DClassification Reflow Profiles
With the component mounted on a PCB with the device to be tested, apply a force(>0805:1kg , <=0805:0.5kg)to the side of a device being tested. This force shall be applied for 60 +1 seconds. Also the force shall be applied gradually as not to apply a shock to the component being tested.
</td></tr>
</table>

Note : When there are questions concerning measurement result : measurement shall be made after 48 ± 2 hours of recovery under the standard condition.

8. Soldering and Mounting

(1) Soldering

Mildly activated rosin fluxes are preferred. The minimum amount of solder can lead to damage from the stresses caused by the difference in coefficients of expansion between solder, chip and substrate. TAI-TECH terminations are suitable for re-flow soldering systems. If hand soldering cannot be avoided, the preferred technique is the utilization of hot air soldering tools.

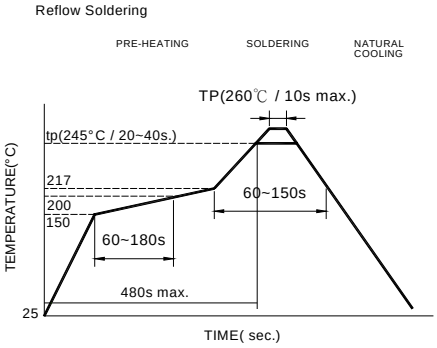
(2) Solder re-flow:

Recommended temperature profiles for re-flow soldering in Figure 1.

(3) Soldering Iron:

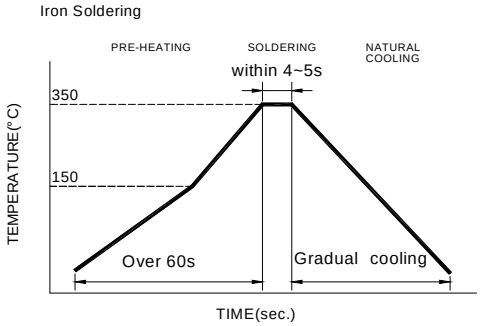
Products attachment with a soldering iron is discouraged due to the inherent process control limitations. In the event that a soldering iron must be employed the following precautions are recommended.

- Preheat circuit and products to 150℃
- Never contact the ceramic with the iron tip
- Use a 20 watt soldering iron with tip diameter of 1.0mm
- 355℃ tip temperature (max)
- 1.0mm tip diameter (max)
- Limit soldering time to 4~5sec.



Reflow times: 3 times max.

Fig.1

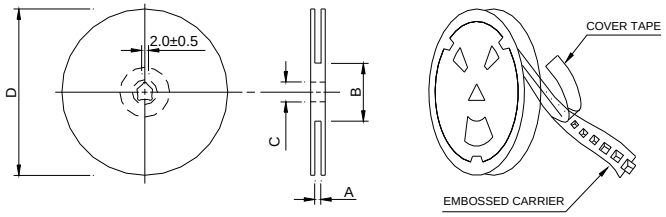


Iron Soldering times: 1 times max.

Fig.2

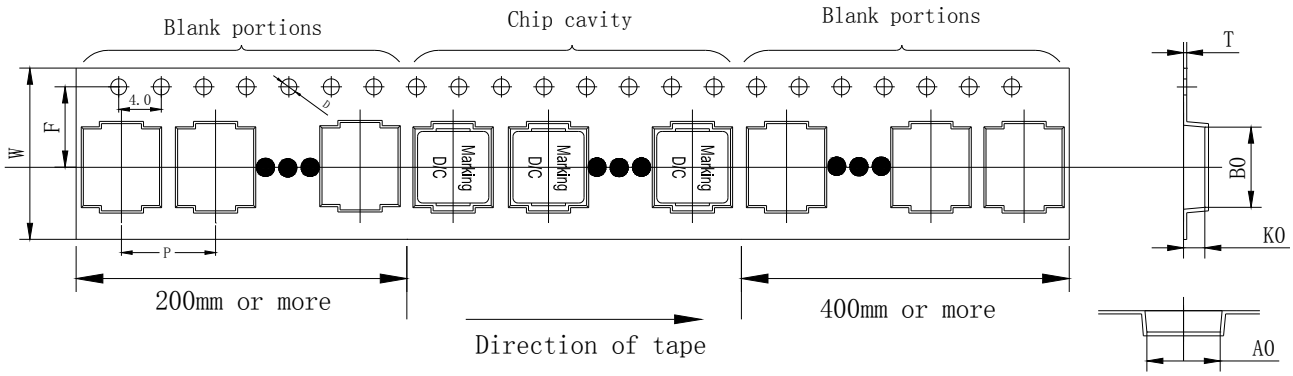
9. Packaging Information

(1) Reel Dimension



Type	A(mm)	B(mm)	C(mm)	D(mm)
13"x24mm	24.4+2/-0	100±2	13+0.5/-0.2	330

(2) Tape Dimension

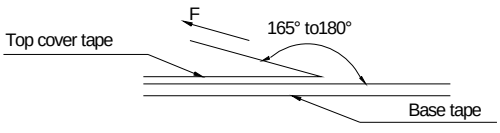


Series	Size	Bo(mm)	Ao(mm)	Ko(mm)	P(mm)	W(mm)	F(mm)	t(mm)	D(mm)
TMPC	1004	11.6±0.1	10.4±0.1	4.5±0.1	16.0±0.1	24±0.3	11.5±0.1	0.35±0.05	1.5±0.1

(3) Packaging Quantity

TMPC	1004
Chip / Reel	500
Inner box	**1000**
Carton	**4000**

(4) Tearing Off Force



The force for tearing off cover tape is 10 to 130 grams in the arrow direction under the following conditions(referenced ANSI/EIA-481-D-2008 of 4.11 stadnard).

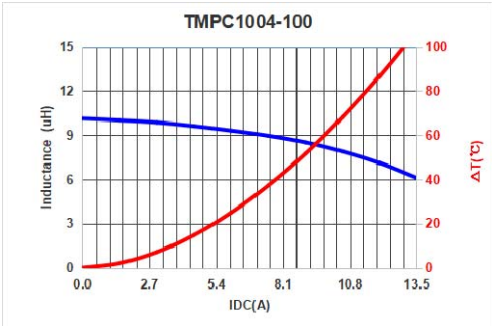
Room Temp. (℃)	Room Humidity (%)	Room atm (hPa)	Tearing Speed mm/min
5~35	45~85	860~1060	300

Application Notice

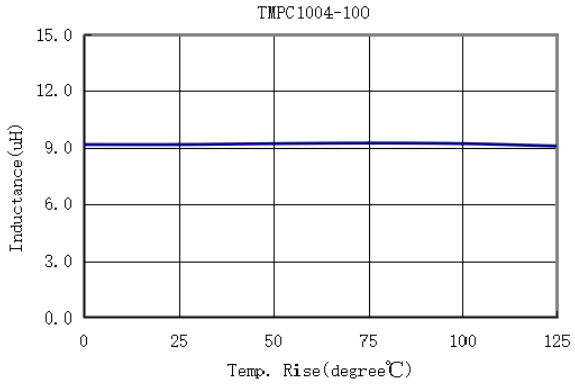
- Storage Conditions
  To maintain the solderability of terminal electrodes:
  1. TAIPAQ products meet IPC/JEDEC J-STD-020D standard-MSL, level 1.
  2. Temperature and humidity conditions: Less than 40℃ and 60% RH.
  3. Recommended products should be used within 12 months form the time of delivery.
  4. The packaging material should be kept where no chlorine or sulfur exists in the air.
- Transportation
  1. Products should be handled with care to avoid damage or contamination from perspiration and skin oils.
  2. The use of tweezers or vacuum pick up is strongly recommended for individual components.
  3. Bulk handling should ensure that abrasion and mechanical shock are minimized.

10. Typical Performance Curves

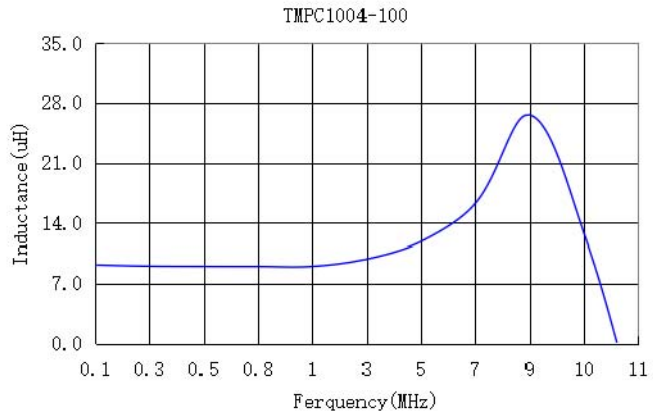
a.Inductance vs. DC Current , Temperature vs. DC Current



b.Inductance vs. DC Thermel



C.Inductance vs. DC Frequency



11. 出貨標籤貼紙編碼原則

11-1.條碼貼紙



貼附位置:料盤下方

條碼材質:銅版紙

條碼紙大小:80*50mm

條碼分辨率:300DPI

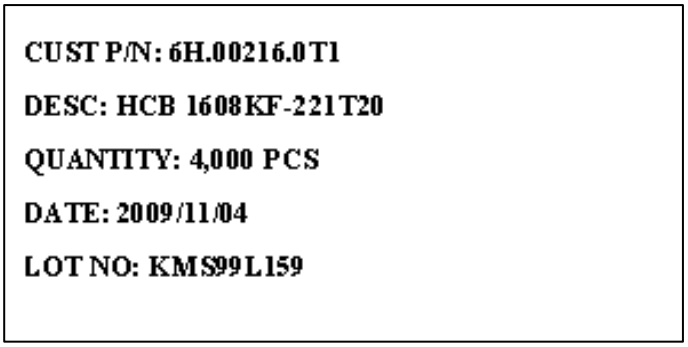
顏色:白紙+黑字

文字字體:Arial

黏貼方式:自黏

條碼內容依 Qisda 要求規範

11-2.內盤標籤貼紙



貼附位置:料盤上方

條碼材質:模造紙

條碼紙大小:88*36mm

顏色:白紙+黑字

文字字體:Roman

黏貼方式:自黏

內容說明:

CUST P/N:QISDA 料號

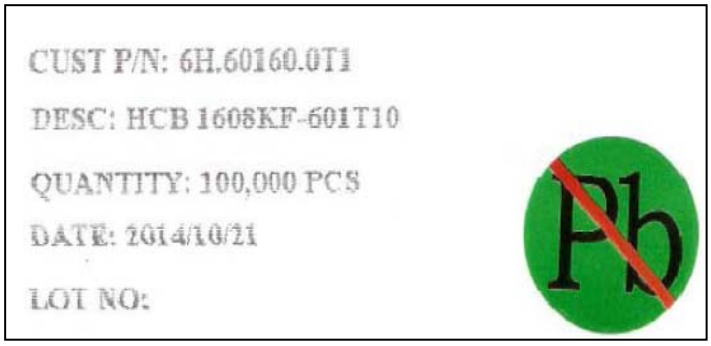
DESC:TAI-TECH 品名

QUANTITY:數量(單位 PCS)

DATE:西曆

LOT NO:英文與阿拉伯數字 7-9 碼

11-3.外箱標籤貼紙



同內盤標籤貼紙+無鉛 Pb 貼紙

貼附位置:外箱左上方